

Maximum Ratings @T_A = 25°C unless otherwise specified

Single phase, half wave, 60Hz, resistive or inductive load.
 For capacitance load, derate current by 20%.

Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage	V _{RRM}	30	V
Working Peak Reverse Voltage	V _{RWM}		
DC Blocking Voltage	V _R		
RMS Reverse Voltage	V _{R(RMS)}	21	V
Average Forward Current	I _{F(AV)}	2.0	A
Non-Repetitive Peak Forward Surge Current 8.3ms Single Half Sine-Wave Superimposed on Rated Load	I _{FSM}	75	A

Thermal Characteristics

Characteristic	Symbol	Typ	Max	Unit
Thermal Resistance Junction to Soldering Point (Note 3)	R _{θJS}	—	6	°C/W
Operating Temperature Range	T _J	-65 to +150		°C
Storage Temperature Range	T _{STG}	-65 to +150		°C

Electrical Characteristics @T_A = 25°C unless otherwise specified

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 4)	V _{(BR)R}	30	—	—	V	I _R = 200μA
Forward Voltage	V _F	—	—	0.45 0.375	V	I _F = 2A, T _J = 25°C I _F = 2A, T _J = 125°C
Leakage Current (Note 4)	I _R	—	—	0.200 15	mA	V _R = 30V, T _J = 25°C V _R = 30V, T _J = 100°C
Total Capacitance	C _T	—	85	—	pF	V _R = 10V, f = 1.0MHz

- Notes:
3. Theoretical R_{θJS} calculated from the top center of the die straight down to the PCB/cathode tab solder junction.
 4. Short duration pulse test used to minimize self-heating effect.
 5. Part mounted on FR-4 board with 2 oz., minimum recommended copper pad layout which can be found on our website at <http://www.diodes.com>.
T_A = 25°C

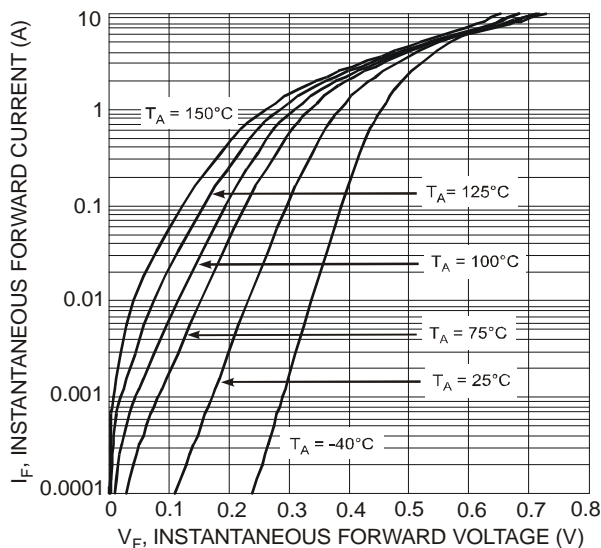


Fig. 1 Typical Forward Characteristics

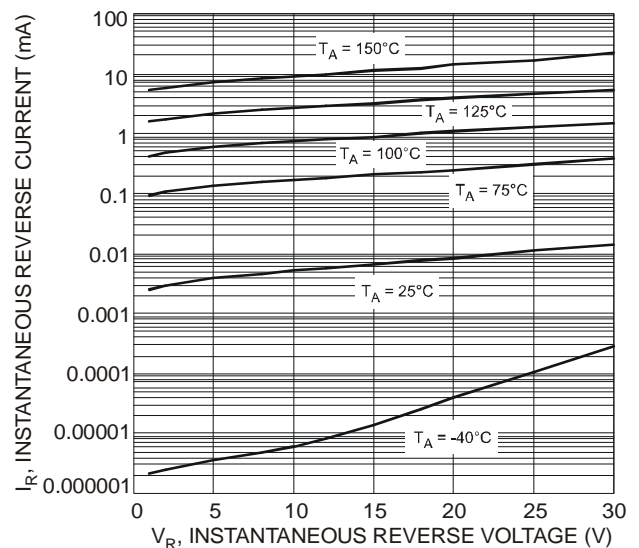


Fig. 2 Typical Reverse Characteristics

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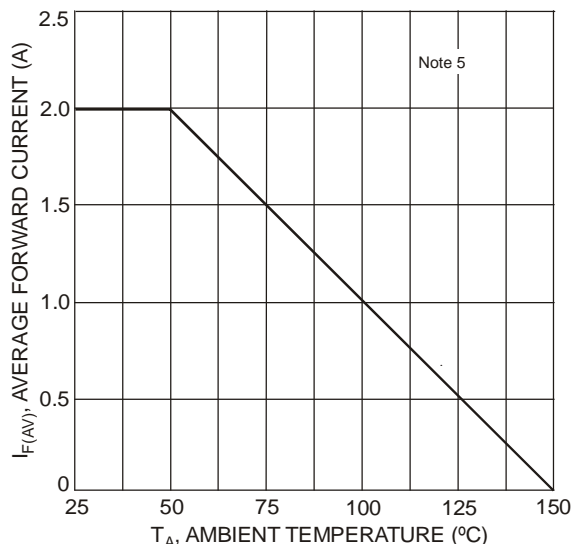
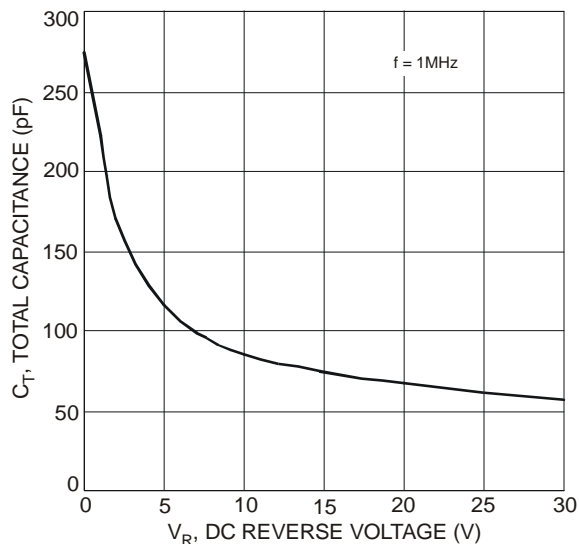
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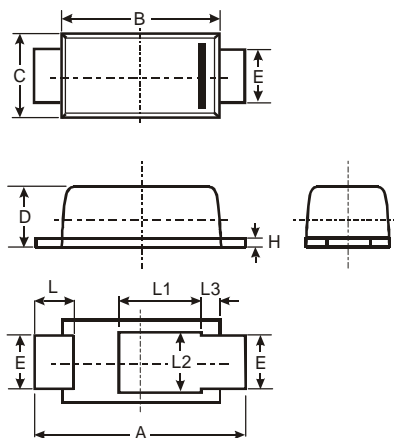
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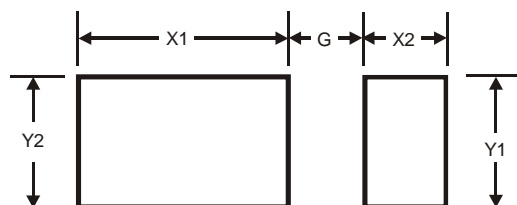


Package Outline Dimensions



POWERDI [®] 123			
Dim	Min	Max	Typ
A	3.50	3.90	3.70
B	2.60	3.00	2.80
C	1.63	1.93	1.78
D	0.93	1.00	0.98
E	0.85	1.25	1.00
H	0.15	0.25	0.20
L	0.40	0.50	0.45
L1	-	-	1.35
L2	-	-	1.10
L3	-	-	0.20
All Dimensions in mm			

Suggested Pad Layout



Dimensions	Value (in mm)
G	1.0
X1	2.2
X2	0.9
Y1	1.4
Y2	1.4

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